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## DESCRIPTION

BUMP FORMING APPARATUS FOR CHARGE APPEARANCE SEMICONDUCTOR SUBSTRATE, CHARGE REMOVAL METHOD FOR CHARGE APPEARANCE SEMICONDUCTOR SUBSTRATE, CHARGE REMOVING UNIT FOR CHARGE APPEARANCE SEMICONDUCTOR SUBSTRATE, AND CHARGE APPEARANCE SEMICONDUCTOR SUBSTRATE

### Technical Field

[0001] The present invention relates to a bump forming apparatus for forming bumps onto a charge appearance type semiconductor substrate such as a piezoelectric substrate or the like which generate electric charge in accordance with a temperature change (that is, a charge appearance semiconductor substrate) a method carried out by the bump forming apparatus for removing charge of the charge appearance semiconductor substrate, a charge removing unit installed in the bump forming apparatus for charge appearance semiconductor substrates, and a charge appearance semiconductor substrate.

### Background Art

[0002] Electronic components installed in devices, e.g., portable phones and the like have been made compact these days in association with a great miniaturization of the devices. There is a bump forming apparatus which forms bumps on electrode parts in circuit form parts formed on a semiconductor wafer without separating the circuit form

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